

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A probe sheet unit being a sensing section of a semiconductor wafer measuring instrument comprising:

a base plate mountable to a prober of the instrument instrument;

a sheet member with a flexibility mounted to the base plate; and

plural measurement probes provided on one surface of the sheet member, wherein the plural measurement probes are ~~arranged on said surface of the sheet member and elastically deformable~~ respectively in response to a force acting on the top thereof for varying proximity from the top of the probe to said sheet member in vertical directions by respectively contacting with a plurality of electrodes arranged on a surface of a measurement objective and

said sheet member ~~in part or in whole~~ is elastically deformable [[by]] in response to a force acting thereon through the respective measurement probes for varying proximity therefrom to said base plate and thereby is capable of vertical displacement.

Claim 2 (previously presented): A probe sheet unit according to claim 1, wherein wiring patterns are formed inside and/or on a surface of the sheet member and an external electrode

Best Available Copy

please
do not
enter in
the file.
Emily
8/17/05